

Quick Infrared BGA7610 Rework Station (2400W)

SKU: GQ-7610-BGA



Features & Benefits

- ◆ **Powerful Heating System:**
- ◆ 2400W Maximum Power: Efficient for high-powered, quick thermal processing.
- ◆ Bottom Preheating Power: 1600W infrared ceramic heating plate ensures optimal thermal distribution across the PCB.
- ◆ Top Heating Power: 720W infrared heating tube (2-8um wavelength) for precise, controlled heat application to BGA components.
- ◆ **Large Working Area:**
- ◆ Bottom Preheating Area: 260x260mm, sufficient for handling a variety of PCB sizes.
- ◆ Max PCB Size: 420x500mm, supports medium to large PCBs for BGA rework applications.
- ◆ Max BGA Size: 60x60mm, suitable for large BGA components.
- ◆ **Infrared Temperature Control:**
- ◆ Non-contact Infrared Sensors: Ensures precise temperature control on the BGA surface without direct contact, preventing potential damage.
- ◆ Temperature Range: 0–300°C, suitable for a wide range of soldering and desoldering applications.
- ◆ Closed-loop Temperature Control: Guarantees even heat distribution and precise temperature control for optimal rework quality.
- ◆ **Precision & Flexibility:**
- ◆ Four-Directional PCB Fixture: Easily adjust the PCB position for accurate alignment, ensuring precision during rework tasks.
- ◆ Top Dark-Infrared Heating: Reduces the vertical temperature difference between the BGA surface and the solder joints, improving soldering efficiency and reducing rework time.
- ◆ **Communication & Data Analysis:**
- ◆ RS-232C Communication: Can be connected to a PC for monitoring and controlling the rework process.
- ◆ IRSOFT Interface: Provides operating authority and profile analysis, enabling users to track and adjust process parameters for optimal rework results.
- ◆ **No Need for Nozzles:**
- ◆ The system uses infrared heating for BGA soldering, eliminating the need for nozzles, simplifying the rework process.
- ◆ The system's advanced features ensure reliable BGA rework results, minimising the risk of PCB damage while providing consistent, even heat distribution

About the Quick Infrared BGA7610 Rework Station (2400W)

The Quick Infrared BGA7610 Rework Station represents cutting-edge technology for BGA (Ball Grid Array) soldering and desoldering.

Using infrared sensor technology, this station is capable of delivering high-precision, non-contact heating with a 2400W maximum power. The system's advanced features ensure reliable BGA rework results, minimising the risk of PCB damage while providing consistent, even heat distribution. The infrared heating process eliminates the need for nozzles and airflow, ensuring high success rates for BGA ball processes. Its large preheating and top heating areas allow for efficient thermal management, making it ideal for medium to large-sized PCBs and BGA components.

The Quick Infrared BGA7610 Rework Station is ideal for BGA soldering and desoldering, particularly for high-density components like BGAs, CSPs (Chip Scale Packages), and QFNs (Quad Flat No-lead). It is perfect for PCB manufacturers, repair stations, and technicians dealing with large and intricate PCBs.

Additional Specifications:

- Max PCB Size: 420x500mm
- Max BGA Size: 60x60mm
- Dimensions: 800x580x520mm
- Weight: 36kg
- Infrared Temperature Sensor: 0–300°C range

Specifications

Property	Detail
Application	ESD-protected areas, electronics mfg, cleanrooms